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United States Patent [19]

Itoh

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[45] **Date of Patent: ** Nov. 30, 1993**

[54] **HEAT DISSIPATING DEVICE FOR A SEMICONDUCTOR PACKAGE**

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[73] Assignee: **Itoh Research & Development Laboratory Co., Ltd.**, Osaka, Japan

[**] Term: **14 Years**

[21] Appl. No.: **933,504**

[22] Filed: **Aug. 21, 1992**

[30] **Foreign Application Priority Data**

Mar. 4, 1992 [JP] Japan 4-6201

[52] **U.S. Cl.** **D13/179**

[58] **Field of Search** D13/179, 182; 437/902; 165/104.33; 257/720; 174/15.2, 16.3; 361/386

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[57] **CLAIM**

The ornamental design for a heat dissipating device for a semiconductor package, as shown and desscribed.

DESCRIPTION

FIG. **1** is a front view of an embodiment of the heat dissipating device;

FIG. **2** is a top plan view thereof;

FIG. **3** is a bottom plan view thereof;

FIG. **4** is a right side view thereof;

FIG. **5** is a perspective view thereof;

FIG. **6** is a sectional view taken along section line **6—6** in FIG. **2**;

FIG. **7** is a sectional view taken along section line **7—7** in FIG. **2**; and,

FIG. **8** is a view of the heat dissipating device shown in FIG. **1** attached to a semiconductor package, the latter being shown by broken lines only as it does not form any part of the claimed design.

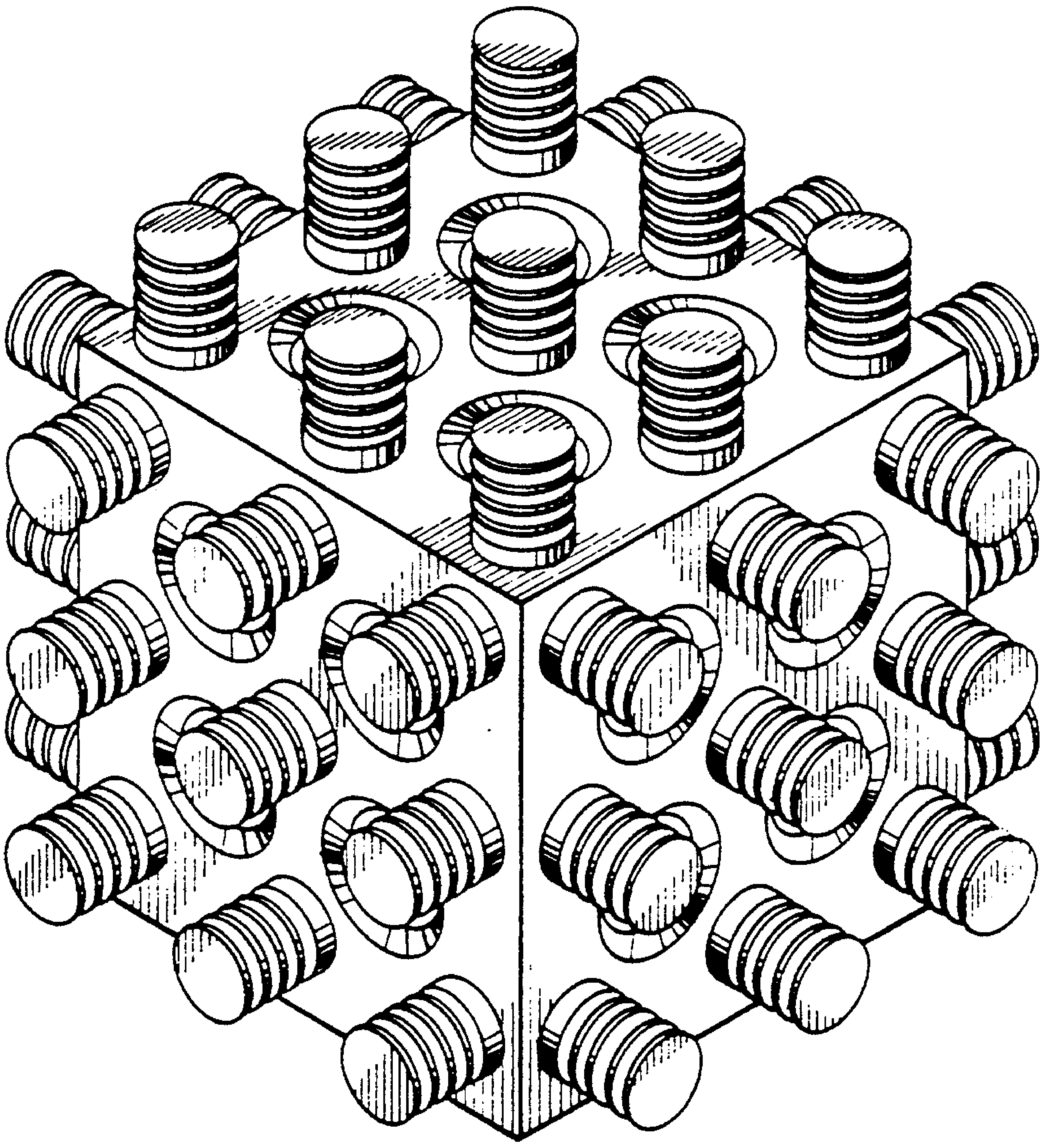

FIG. 1

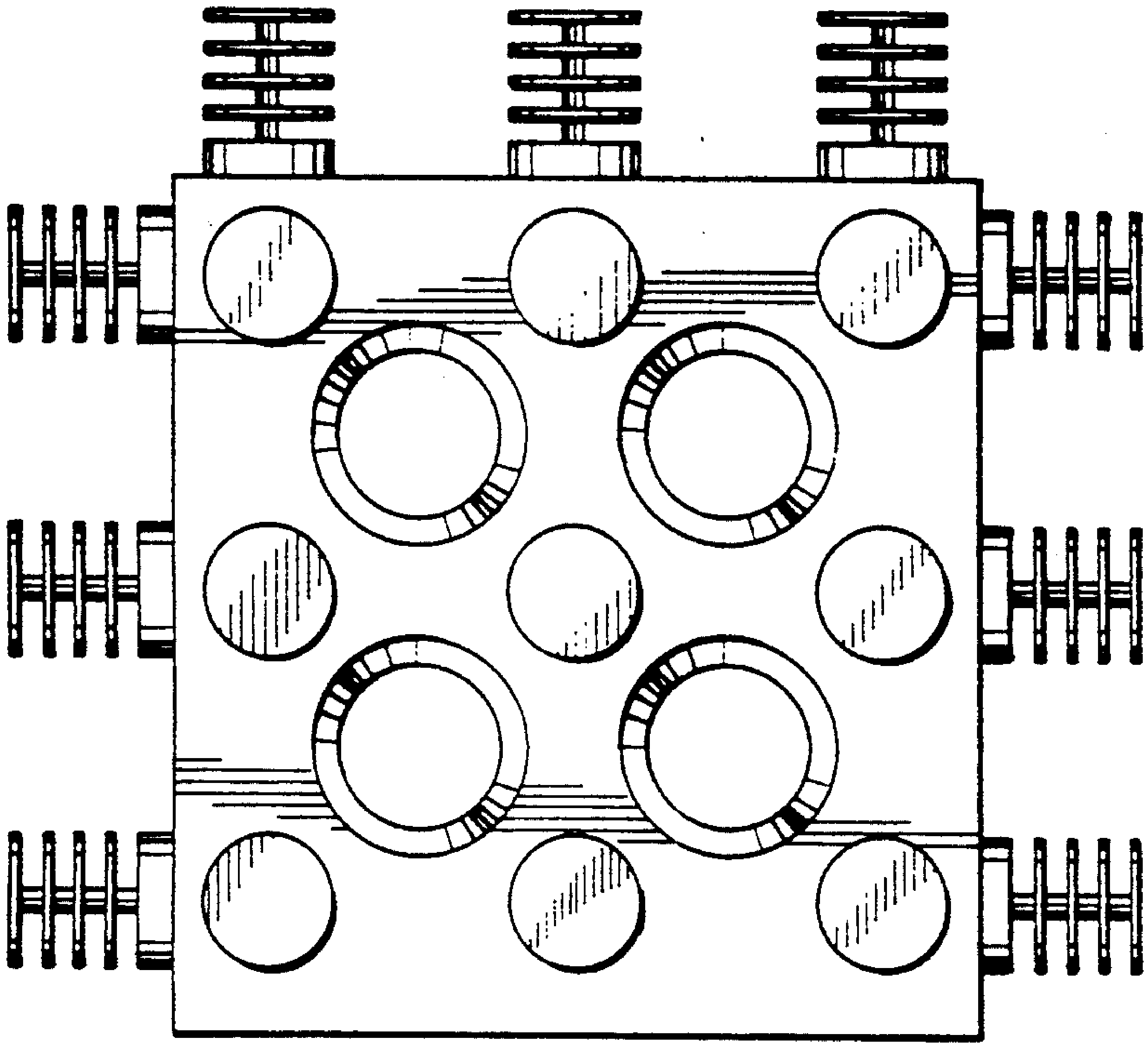

FIG. 4

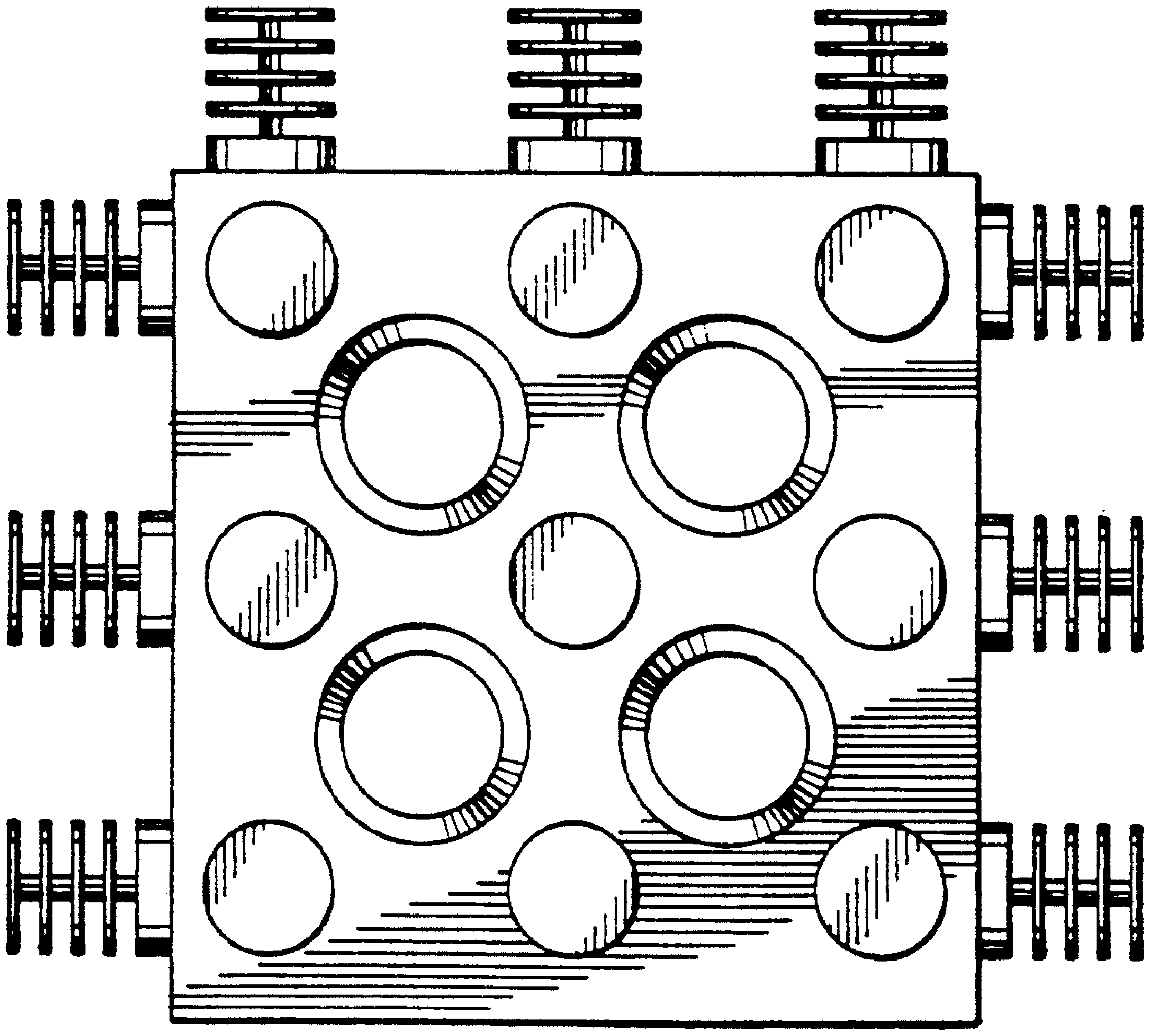

FIG. 2

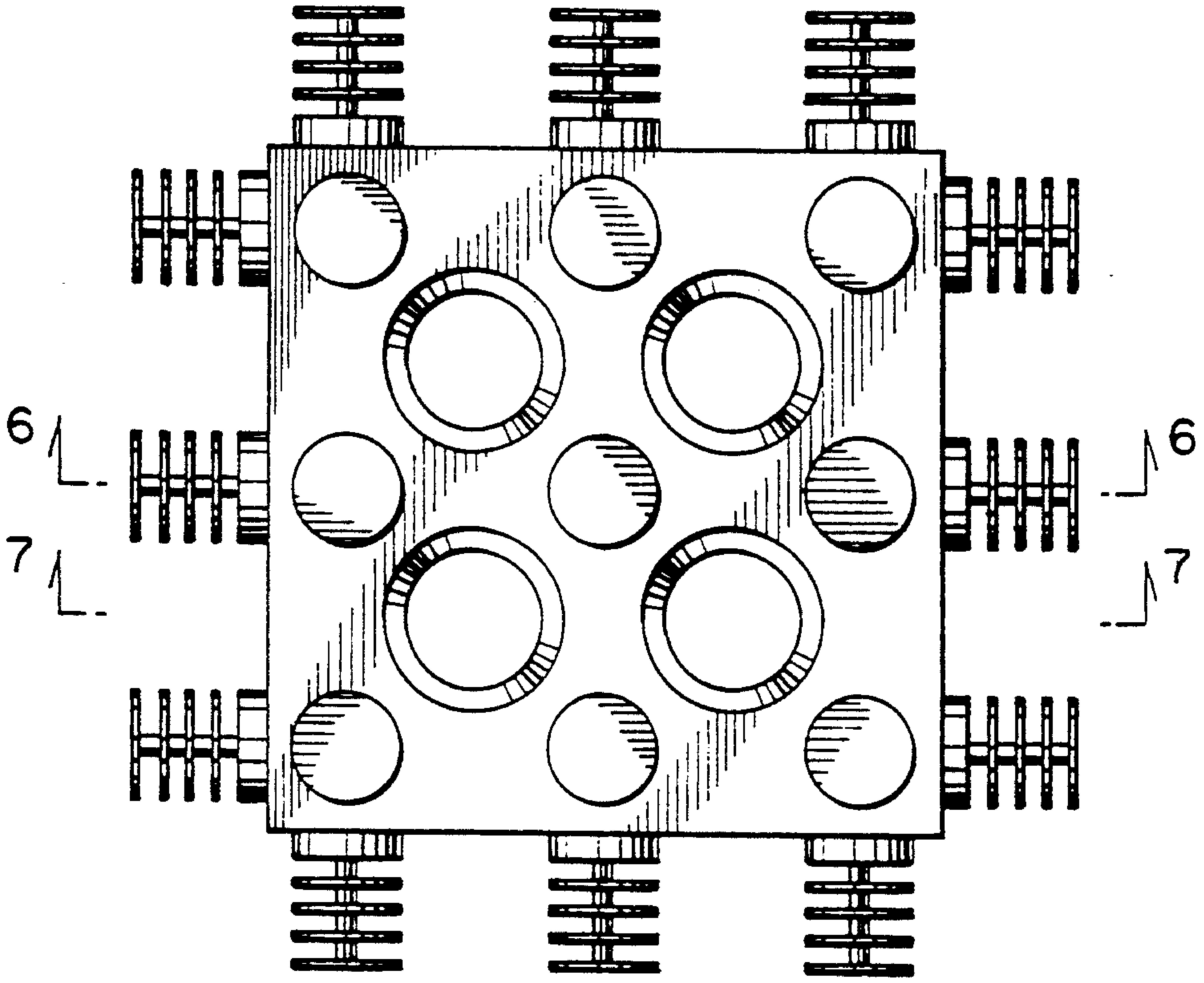

FIG. 3

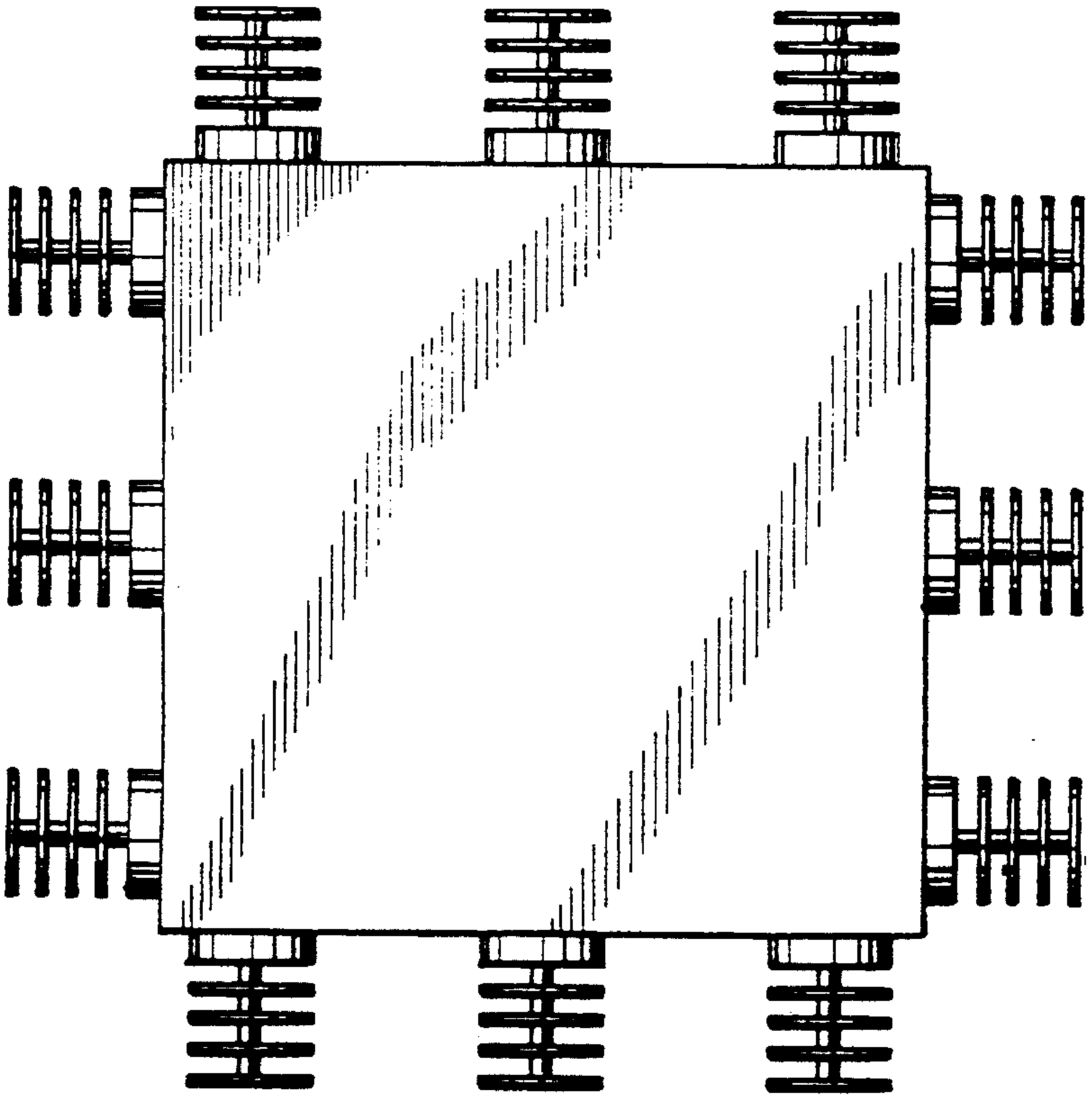

FIG. 5

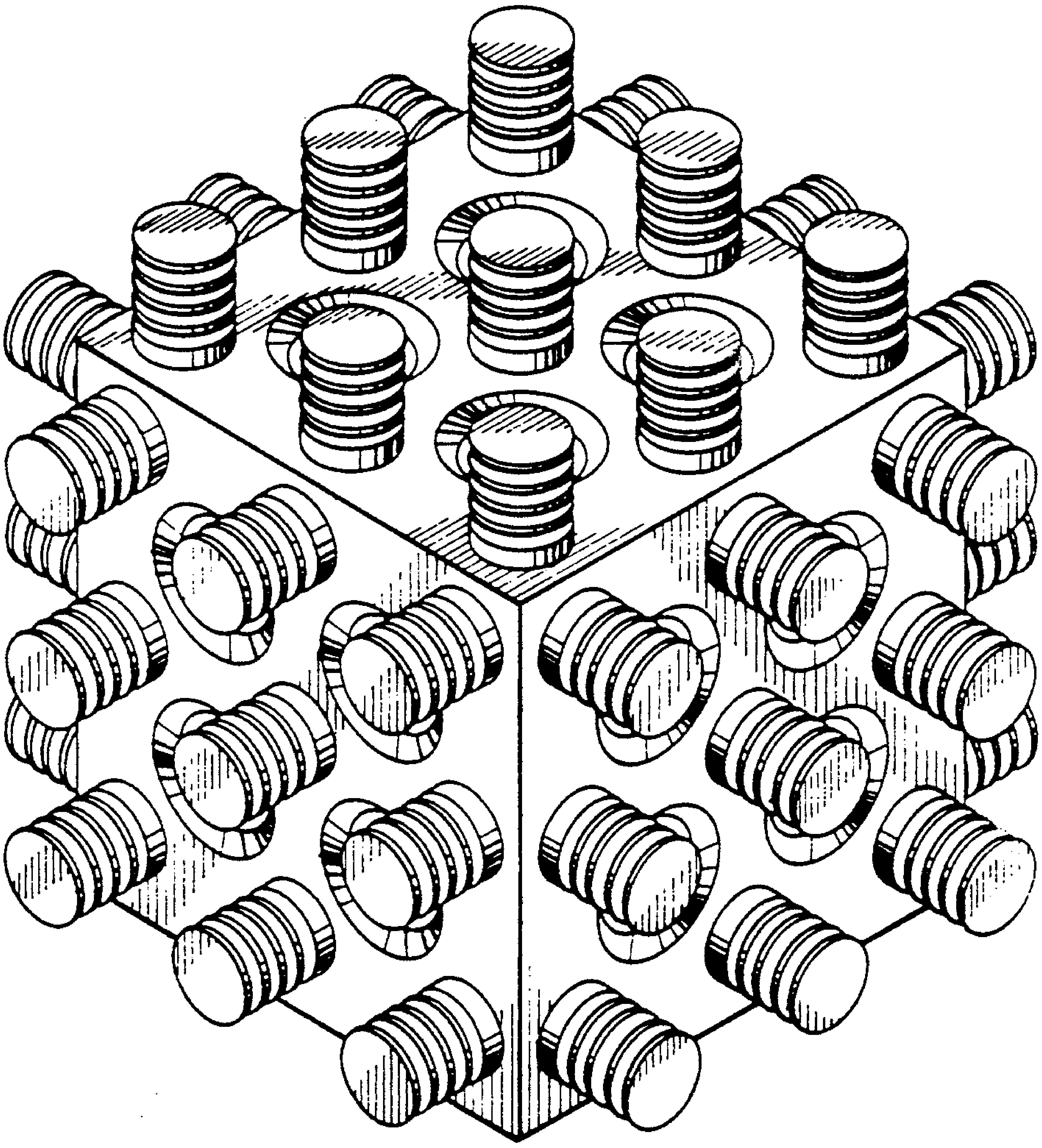

FIG. 6

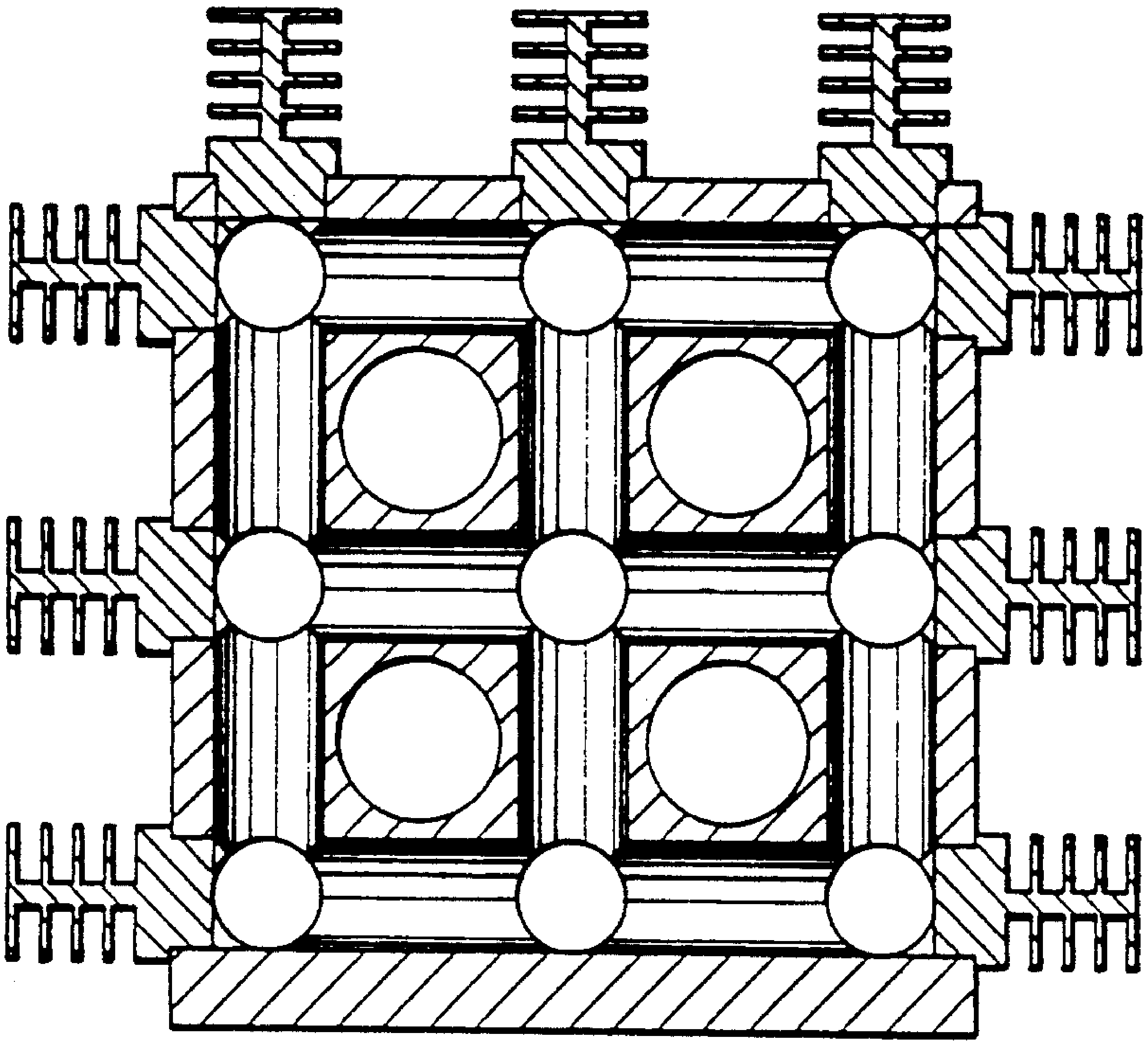

FIG. 7

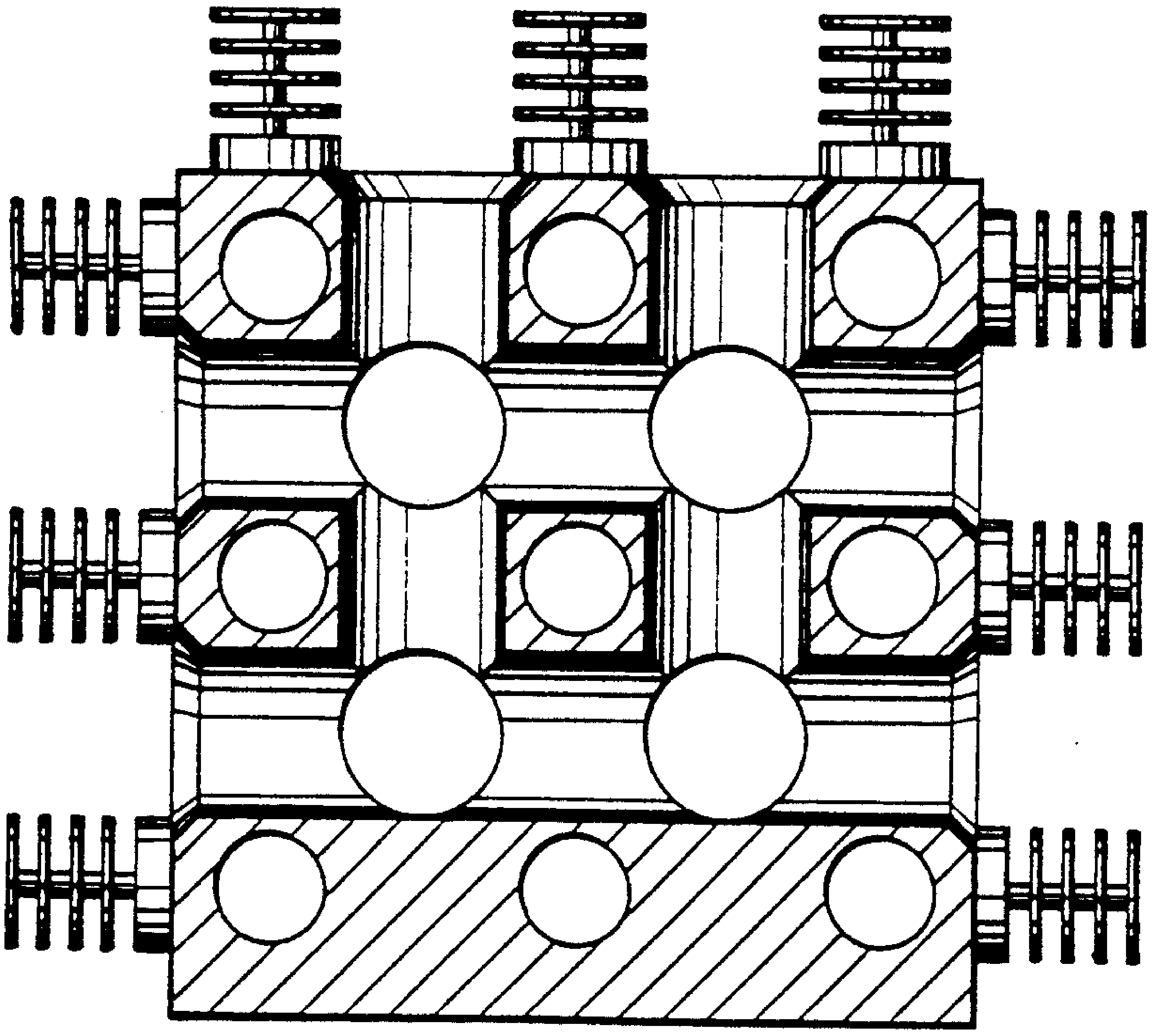

FIG. 8